

MEC1 SERIES

(1.00 mm) .0394"

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over 50 μ" (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

2.2 A per pin (2 adjacent pins powered)

Voltage Rating:

300 VAC

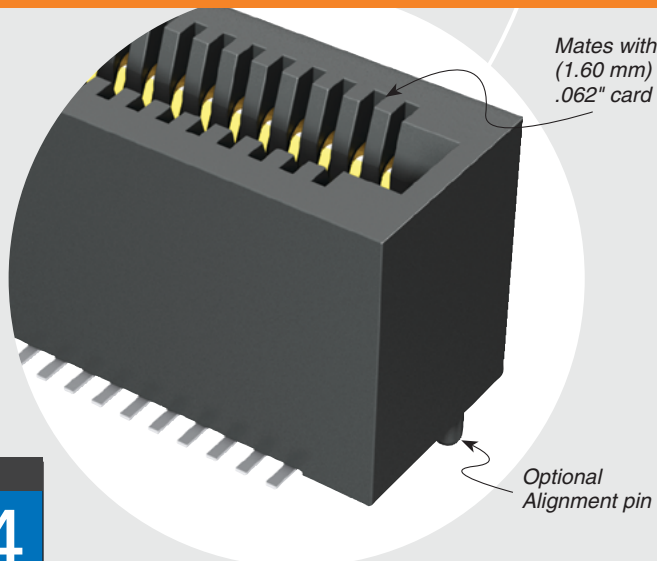
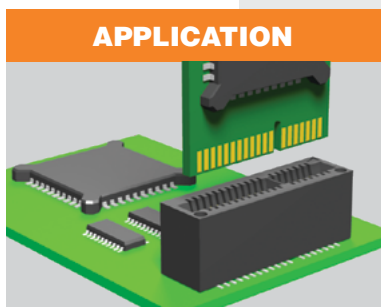
Insertion Depth:

(5.84 mm) .230" to (8.13 mm) .320"

RoHS Compliant:

Yes

Mates with:
(1.60 mm) .062" card



HIGH-SPEED CHANNEL PERFORMANCE

MEC1
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

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PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (05-20),
(0.15 mm) .006" max (30-70)*
*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE

(MOQ Required)

- Locking Clip (Manual placement required)
- Other platings

Important Note:

Samtec recommends that pads on the mating board be Gold plated.

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some sizes, styles and options are non-standard, non-returnable.

MEC1 - **1** POSITIONS PER ROW - **02** - **PLATING OPTION** - **D** - **NP** - **OTHER OPTION**

05, 08, 20, 30, 40, 50, 60, 70

-F
= Gold flash on contact, Matte tin on tail

-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-NP
= No Polarization (05, 08, 20 & 30 positions only)
Leave Blank for polarization

-A
= Alignment Pin metal or plastic at Samtec discretion.

-K
= (7.87 mm) .310" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel (05-60 only)

POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

